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QFET[®]



FQP3N50C/FQPF3N50C 500V N-Channel MOSFET

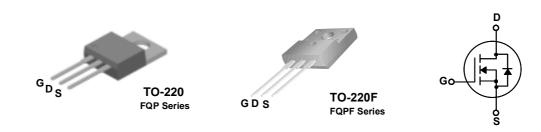
Features

- + 3 A, 500 V, ${\sf R}_{\sf DS(on)}$ = 2.5 Ω @ V_{\sf GS} = 10 V
- Low gate charge (typical 10 nC)
- Low Crss (typical 8.5 pF)
- Fast switching
- 100 % avalanche tested
- Improved dv/dt capability

Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.



Absolute Maximum Ratings

| Symbol | | Parameter | | FQP3N50C | FQPF3N50C | Units |
|-----------------------------------|---|------------------------------------|----------|-------------|-----------|-------|
| V _{DSS} | Drain-Source Voltage | | | Ę | V | |
| I _D | Drain Current - Continuous (T _C = 25°C) | | | 3 3* | | А |
| | | - Continuous (T _C = 100 |)°C) | 1.8 | 1.8 * | А |
| I _{DM} | Drain Current | - Pulsed (Note 1) | | 12 | 12 * | А |
| V _{GSS} | Gate-Source Voltage | | | ± | V | |
| E _{AS} | Single Pulsed Avalanche Energy | | (Note 2) | 200 | | mJ |
| I _{AR} | Avalanche Current | | (Note 1) | 3 | | А |
| E _{AR} | Repetitive Avalanche Energy | | (Note 1) | 6.2 | | mJ |
| dv/dt | Peak Diode Recovery dv/dt | | (Note 3) | 4.5 | | V/ns |
| PD | Power Dissipation ($T_C = 25^{\circ}C$) | | | 62 | 25 | W |
| | | - Derate above 25°C | | 0.5 | 0.2 | W/°C |
| T _J , T _{STG} | Operating and Storage Temperature Range | | | -55 to +150 | | °C |
| Τ _L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | | 300 | | °C |

^t Drain current limited by maximum junction temperature

Thermal Characteristics

| Symbol | Parameter | FQP3N50C | FQPF3N50C | Units | |
|-----------------------|---|----------|-----------|-------|--|
| $R_{	extsf{	heta}JC}$ | Thermal Resistance, Junction-to-Case | 2.0 | 4.9 | °C/W | |
| $R_{\theta JS}$ | Thermal Resistance, Case-to-Sink Typ. | 0.5 | | °C/W | |
| $R_{	extsf{	heta}JA}$ | Thermal Resistance, Junction-to-Ambient | 62.5 | 62.5 | °C/W | |

| Device Marking FQP3N50C FQPF3N50C | | Device | Pac | kage | Reel Siz | е | Tape W | 'idth | Quantity | |
|---|---|--|--|---|--|----------|--------|-------|----------|------|
| | | FQP3N50C | TO | O-220 | | | | | 50 | |
| | | FQPF3N50C TO | | 220F | | | | 50 | | |
| Electrica | l Cha | racteristics T _c | = 25°C unles | s otherwise no | ted | | | | | |
| Symbol | ol Parameter | | Test Conditions | | Min. | Тур. | Max. | Units | | |
| Off Character | ristics | | | | | | | | | |
| BV _{DSS} | 1 | Source Breakdown Volt | age | V _{GS} = 0 V, I _D = 250 μA | | | 500 | | | V |
| ΔBV _{DSS} / ΔT _J | | Breakdown Voltage Temperature Coefficient | | | $I_D = 250 \ \mu\text{A}$, Referenced to 25°C | | | 0.7 | | V/°C |
| I _{DSS} | | | ent | V _{DS} = 500 V, V _{GS} = 0 V | | | | | 1 | μA |
| | | - | | $V_{\rm DS} = 400 \text{ V}, \text{ T}_{\rm C} = 125^{\circ}\text{C}$ | | | | | 10 | μΑ |
| I _{GSSF} | Gate-B | ody Leakage Current, | V _{GS} = 30 V, V _{DS} = 0 V | | | | | 100 | nA | |
| I _{GSSR} | Gate-B | ody Leakage Current, | V _{GS} = -30 V, V _{DS} = 0 V | | | | | -100 | nA | |
| On Character | istics | | | | | | | | | |
| V _{GS(th)} | Gate T | Threshold Voltage | | V _{DS} = V _{GS} , I _D = 250 μA | | 2.0 | | 4.0 | V | |
| R _{DS(on)} | | c Drain-Source tesistance | | V _{GS} = 10 V, I _D = 1.5 A | | | | 2.1 | 2.5 | Ω |
| 9 _{FS} | Forwar | d Transconductance | | V _{DS} = 40 | V, I _D = 1.5 A | (Note 4) | | 1.5 | | S |
| Dynamic Cha | racterist | ics | | • | | | | | | • |
| C _{iss} | 1 | Capacitance $V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V},$ | | | V, V _{GS} = 0 V, | | | 280 | 365 | pF |
| C _{oss} | Output | ut Capacitance | | f = 1.0 MHz | | | | 50 | 65 | pF |
| C _{rss} | Revers | Reverse Transfer Capacitance | | | | | | 8.5 | 11 | pF |
| Switching Ch | aracteris | stics | | • | | | | | | |
| t _{d(on)} | Turn-On Delay Time | | | V _{DD} = 250 V, I _D = 3 A, | | | | 10 | 30 | ns |
| t _r | Turn-O | urn-On Rise Time urn-Off Delay Time | | $R_G = 25 \Omega$ | | | | 25 | 60 | ns |
| t _{d(off)} | Turn-O | | | | | | | 35 | 80 | ns |
| t _f | Turn-O | ff Fall Time | | | (Note 4, 5) | | | 25 | 60 | ns |
| Q _g | Total G | ate Charge | | V _{DS} = 400 V, I _D = 3 A, | | | | 10 | 13 | nC |
| Q _{gs} | Gate-S | ource Charge | | | V _{GS} = 10 V | | | 1.5 | | nC |
| Q _{gd} | Gate-D | rain Charge | (Note 4, 5) | | | | 5.5 | | nC | |
| - | Diada C | herests visting and Ma | | tingen | | | | | | |
| I _S | Diode Characteristics and Maximum Ratings Maximum Continuous Drain-Source Diode Forward Current | | | | | | | 3 | A | |
| I _{SM} | Maxim | Maximum Pulsed Drain-Source Diode Fo | | | rward Current | | | | 12 | А |
| V _{SD} | Drain-S | Source Diode Forward | Voltage | | | | | 1.4 | V | |
| t _{rr} | | e Recovery Time | - | $V_{GS} = 0 V, I_S = 3 A,$ | | | 170 | | ns | |
| Q _{rr} | Rever | e Recovery Charge | | $dl_{\rm F}/dt = 100 \text{ A}/\mu \text{s}$ (Note 4) | | | | 0.7 | | μC |

1. Repetitive Rating : Pulse width limited by maximum junction temperature

2. L = 40mH, I_{AS} = 3A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C

3. I_{SD} \leq 3A, di/dt \leq 200A/µs, V_{DD} \leq BV_{DSS,} Starting ~T_J = 25°C

4. Pulse Test : Pulse width $\leq 300 \mu s, \, Duty \, cycle \leq 2\%$

5. Essentially independent of operating temperature

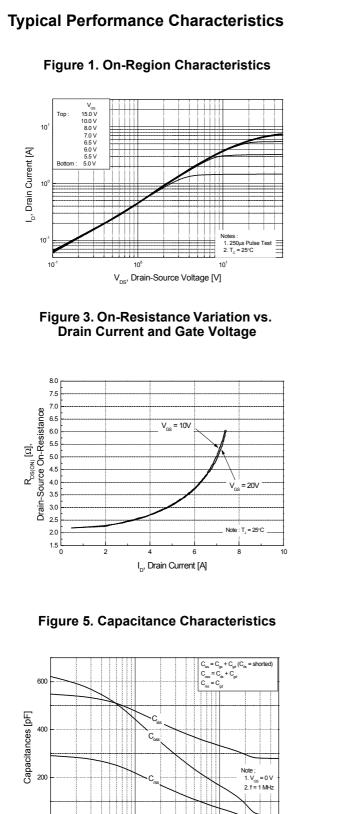
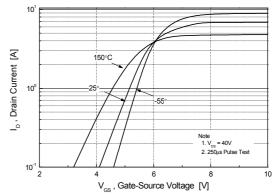
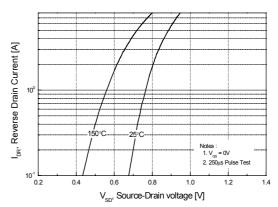


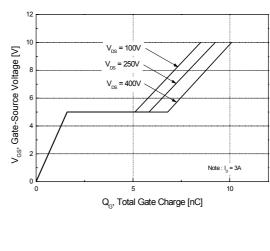
Figure 2. Transfer Characteristics









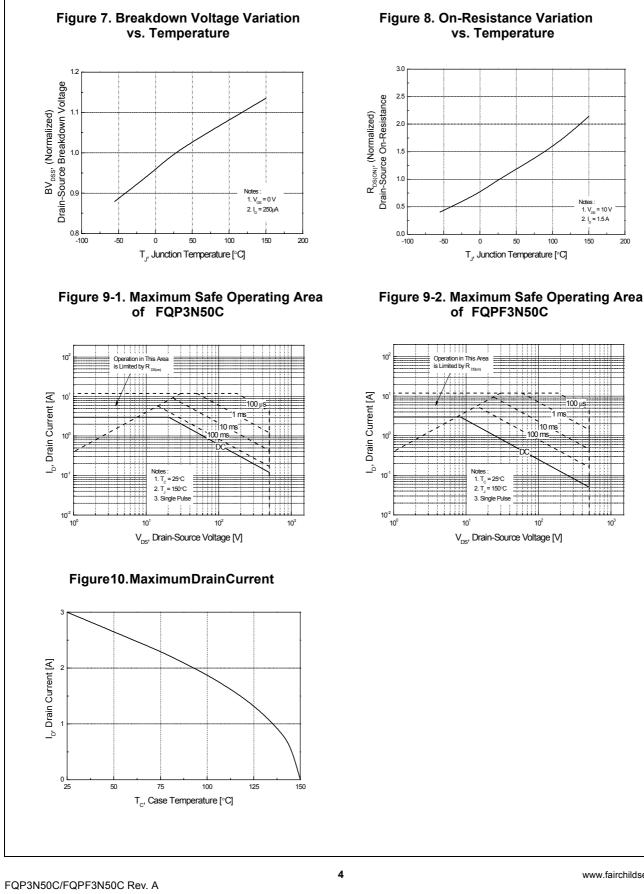


0 L

10⁰

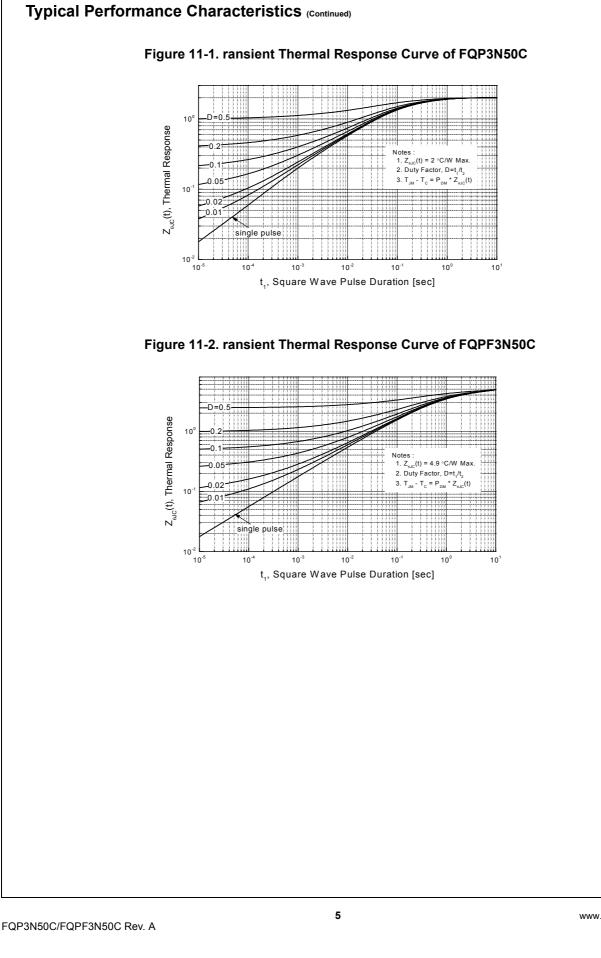
V_{DS}, Drain-Source Voltage [V]

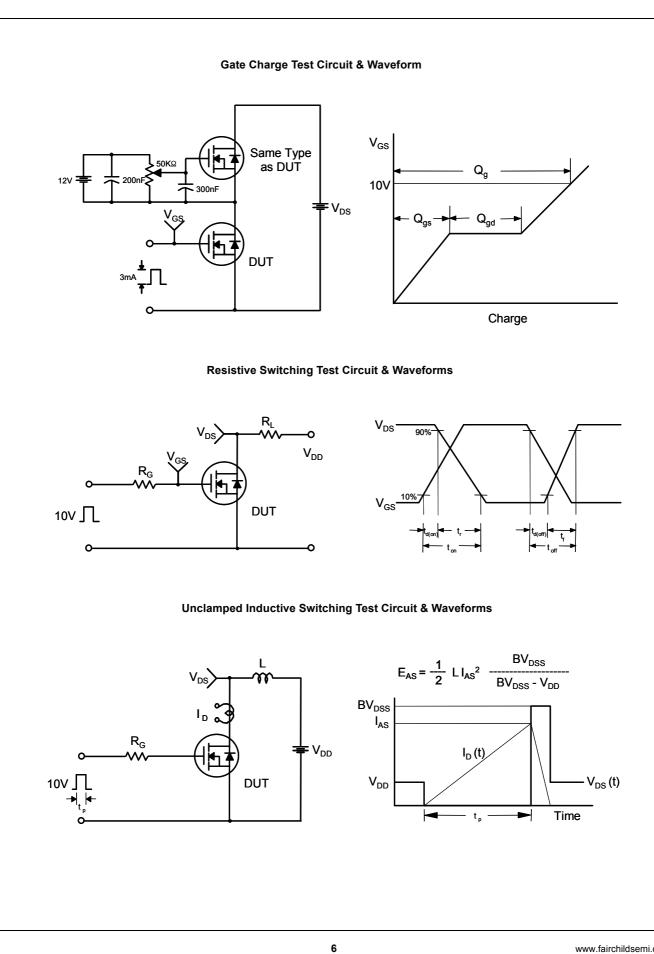
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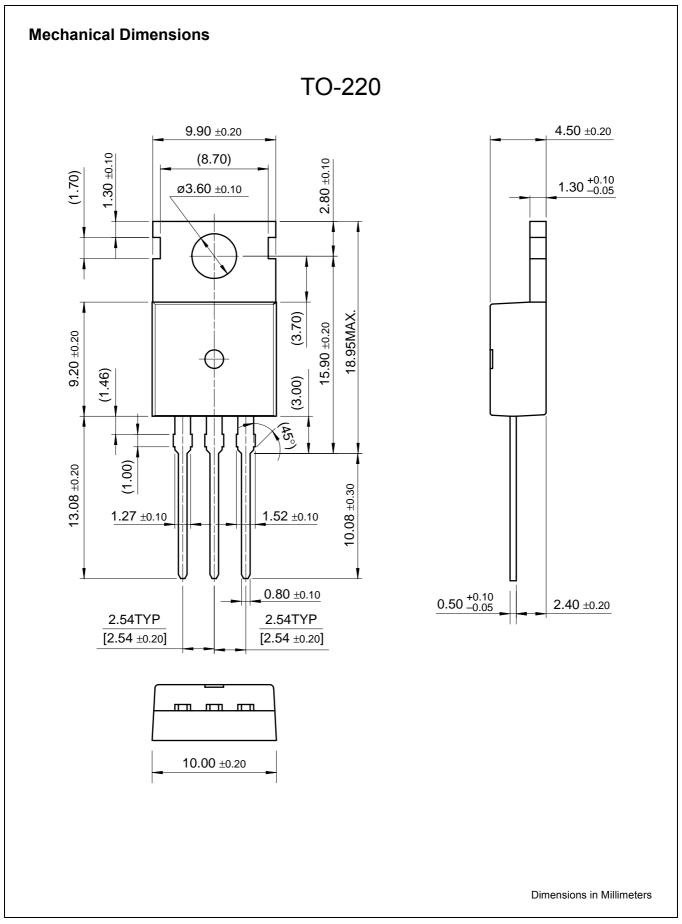
Typical Performance Characteristics (Continued)

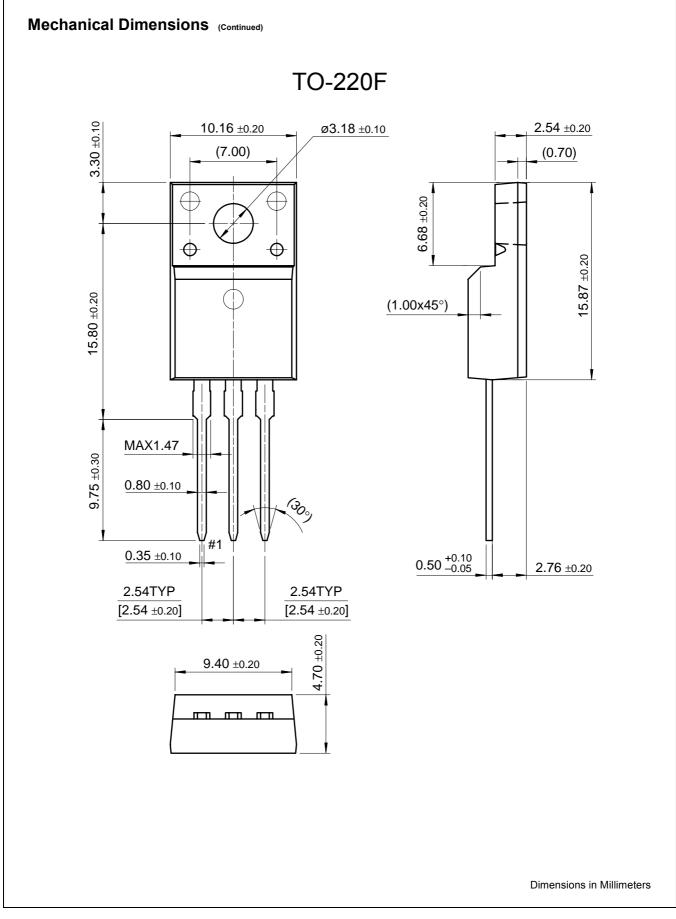
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Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT I_{SD} o o L Driver Same Type as DUT ≢ v₀₀ ∏∏ V_{GS} - dv/dt controlled by R_{G} - \mathbf{I}_{SD} controlled by pulse period C 1 Gate Pulse Width V_{GS} D = Gate Pulse Period 10V (Driver) Ţ \mathbf{I}_{FM} , Body Diode Forward Current I _{SD} di/dt (DUT) I_{RM} Body Diode Reverse Current V_{DS} (DUT) Body Diode Recovery dv/dt t V_{DD} V_{SD} Body Diode Forward Voltage Drop





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